

Abstract

Chip capacitors 20 are provided in a printed circuit board 10. In this manner, the distance between an IC chip 90 and each chip capacitor 20 is shortened, and the loop inductance is reduced. In addition, the chip capacitors 20 are accommodated in a core substrate 30 having a large thickness. Therefore, the thickness of the printed circuit board does not become large.

FIG. 10 is a cross-sectional view of the printed circuit board 10 according to the second embodiment of the present invention. The printed circuit board 10 includes a core substrate 30 having a large thickness. A chip capacitor 20 is mounted on the core substrate 30. An IC chip 90 is mounted on the printed circuit board 10. The distance between the IC chip 90 and the chip capacitor 20 is shortened. The loop inductance is reduced. In addition, the chip capacitor 20 is accommodated in the core substrate 30 having a large thickness. Therefore, the thickness of the printed circuit board 10 does not become large.